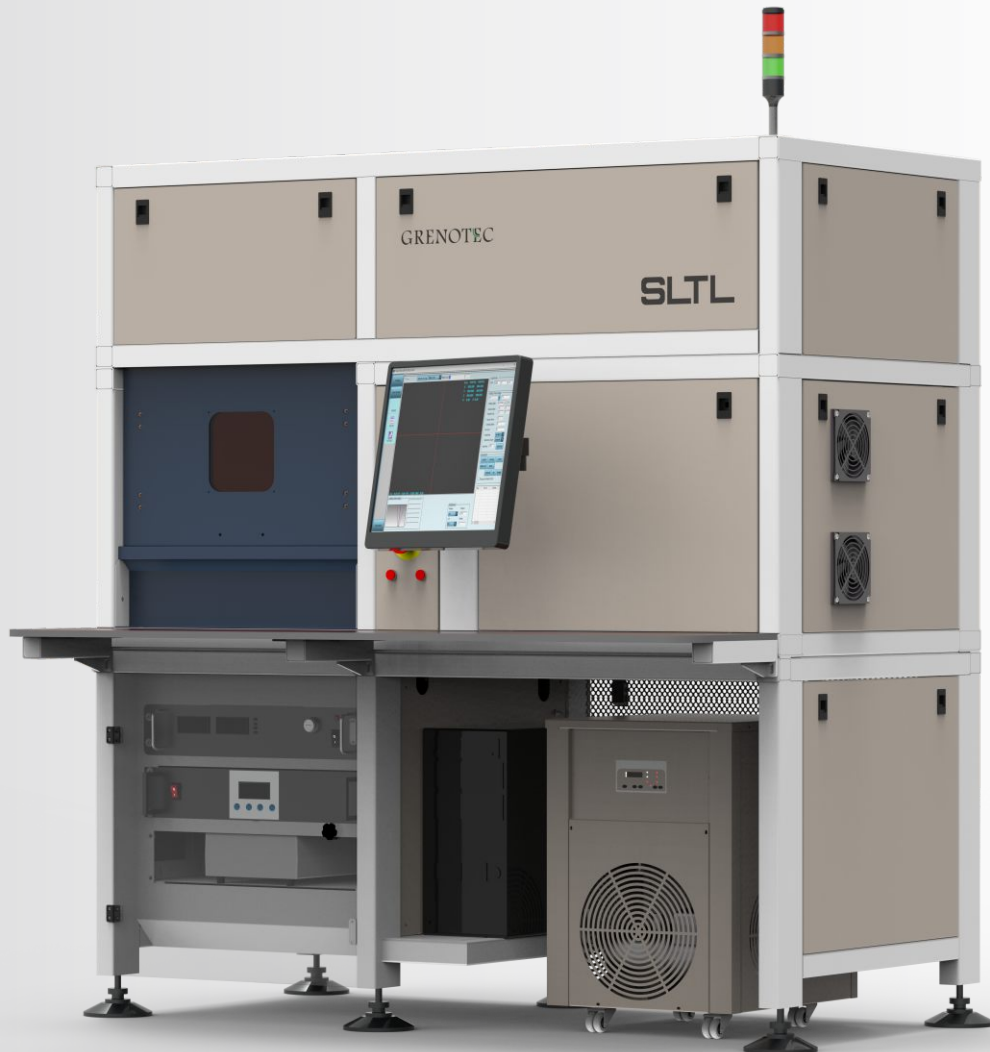


Semiconductor wafer processing system



GRENOTEC

*The product view may vary slightly from the actual product to improve reliability or design

SPECIFICATIONS

Wave Length	532 nm
Working Power	8 - 15 Watt
CNC Table	180 × 180 mm
Beam Spot	≤20-25 μm (depend on optics config.)
Accuracy	±2 μm
Power Supply	230 VAC+/- 10 %, Single Phase
Dimension	1400 × 975 × 1700 mm (approx.)
Computer System	Intel® Core™ i3 based CPU or higher
Warm-up Time	< 5minutes
Cooling Method	Water-cooled
Power Stability	±5%
Polarization	Linear
Controller Interface	RS232/USB/Ethernet

*Product specification and data are subject to change or vary without notice to improve reliability function or design.

FEATURES

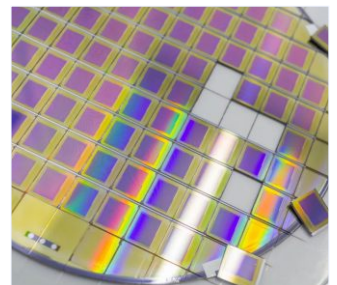
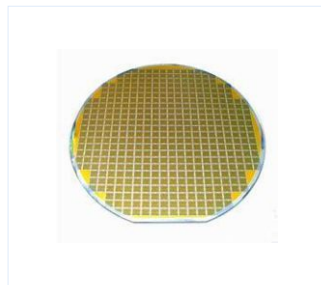
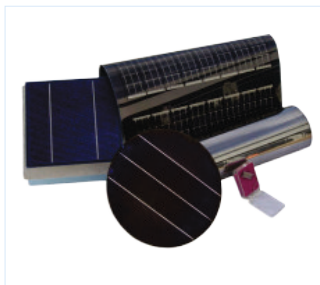
- High Precision
- Compact Rugged Laser
- Water Cooling
- RS232 / USB Port / Ethernet
- Camera Vision System for The Positioning of Substrate
- User Specific Application Software

APPLICATIONS

- Wafer Dicing
- Material Processing
- Drilling
- Micro Cutting
- Ablation

OPTIONAL ACCESSORIES

Vacuum fixed chuck of size (200 mm x 200 mm) / User specific sizes available



Fiber laser cutting machine
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Systems

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Group

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+91-99-2503-6495 | mkt@SLTL.com | www.SLTL.com



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